EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	4	Shi-Jia.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 16:22
S3	6	tan-kah-ong.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/30 09:47
S5	265	348/87.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 16:26
S6	154	348/94.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 07:54
S7	176	348/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 16:54
S10	346	348/374.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:15
S12	870	348/373.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 08:06
S13	452	348/340.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 08:06
S14	472	348/375.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 11:46

S15	125	photosensitive near "circuit board"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/27 08:50
S18	25	"image capturing module" and "circuit board"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/27 09:40
S19	744	348/294.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/27 10:46
S20	458	438/64.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/27 11:22
S21	735	348/335.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/27 16:14
S22	1415	250/239.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 09:23
S23	601	361/725.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 09:38
S24	430	257/729.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 09:39
S25	946	257/730.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 09:55
S26	211	257/733.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 10:03

S27	1183	257/433.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 10:07
S28	307	438/25.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 11:24
S29	469	438/26.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 11:28
S30	360	438/51.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 14:28
S31	191	438/55.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 14:38
S32	261	438/65.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 14:49
S33	3589	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 17:29
S34	184	438/116.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 14:59
S35	7	"5081327"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:08
S36	38	"5302778"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:08

S38	1752726	peg$1 stud$1 dowel$1 tab$1 post$1 leg$s	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:11
S39	12181320	(camera "imaging device" "image pickup") adj$2 (device module apparatus)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:17
S40	179742	(light imag$3 optical) adj sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:13
S41	1069452	S38 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:18
S42	24856	S38 and S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:17
S43	1454373	(camera "imaging device" "image pickup") adj$2 (module)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:25
S44	420918	"circuit board"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:18
S45	211562	S43 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:19
S46	62174	S43 and S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:19
S47	27241	S44 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:20

S48	6912	S44 and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:20
S49	406096	photodetector photosensitive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:20
S50	1465	S49 and S48	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:21
S51	2458	S49 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:21
S52	4035	(camera "imaging device" "image pickup") adj (module)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:26
S53	243	S52 and S44 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:41
S54	287	plastic and S38 and melt and "photosensitive" and "circuit board"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:42
S55	491	plastic and S38 and melt$3 and "photosensitive" and "circuit board"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 15:42
S56	97	bolt$3 with PCB with secur$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 17:15
S59	32	PCB with secur$5 with melt$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 17:02

S66	17	"5783815"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 17:05
S67	2	"2002118776"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/28 17:05
S68	489	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) and (melt$3 solder$3 cur$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 11:35
S69	30	348/373.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) and (melt$3 solder$3 cur$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 08:59
S70	195	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) and (melt$3 solder$3 cur$3 fus$3 heat$3 smelt$3) and (PCB "circuit board") and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:03
S71	31	(leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) with (melt$3 solder$3 cur$3 fus$3 heat$3 smelt$3) and (PCB "circuit board") and ("camera module" "image pickup module" "imaging device module")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:09
S72	4569	(leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) with (melt$3 solder$3 cur$3 fus$3 heat$3 smelt$3) and (PCB "circuit board") and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:11
S73	435966	photodetector photosens$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:11
S74	400	S72 and S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:15

S75	4	"6392688"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:15
S76	4	"6741286"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:15
S77	485	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) and (melt$3 solder$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 10:16
S78	166	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1) with (melt$3 solder$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:38
S79	17	"6642613"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:36
S80	286	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1 pin$1) with (melt$3 solder$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 09:39
S81	741	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1 pin$1) and (melt$3 cur$3 solder$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 11:28
S82	321	438/106.ccls. and (leg$1 post$1 peg$1 stud$1 tab$1 dowel$1 pin$1) with (melt$3 cur$3 solder$3 fus$3 heat$3 smelt$3) and (PCB "circuit board")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 10:17
S83	872	348/373.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:04
S84	88	S83 and seal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 11:47

S85	3	S83 and sealant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 11:47
S89	18	348/373.ccls. and light with (seal or glue or potting adhe$4 solder apoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:12
S91	5	348/373.ccls. and "light tight" same (seal or glue or potting adhe$4 solder apoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:13
S92	155	348/374.ccls. and (seal apoxy glue potting adhe$4 solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:16
S93	1	348/374.ccls. and "light tight"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:26
S94	3	348/374.ccls. and ("light tight" or "light impenetrable")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:26
S95	149497	light with (shield$3 opaque impenetrable tight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:46
S96	1741	348/373-376.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:46
S97	139	S96 and S95	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 15:46
S98	2	"7084922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:08

S99	2	"6977187"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:44
S100	22173	(PCB "circuit board") and (CMOS CCD)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:45
S101	8718	(PCB "circuit board") and (CMOS CCD) and module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:45
S102	14	(PCB "circuit board") and (CMOS CCD) and "image pickup module"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:46
S103	364	(PCB "circuit board") and (CMOS CCD) and "camera module"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:49
S105	4	"6741286"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/30 09:48
S107	122	348/373-376.ccls. and (washer or gasket)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/30 10:02
S108	304	348/373-376.ccls. and (washer or gasket or flange)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/30 10:05
S109	200	348/373-376.ccls. and (adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/30 10:05